

High Efficiency, 2.5A, Multi-Cell Li-Ion Battery Charger

General Description

The SY20741B is a multi-cell Li-lon battery stepdown charger designed for 4-14V input range, which can deliver a charge current of up to 2.5A. The charge current can be adjusted using an external resistor, offering flexibility for various portable applications.

The charger features programmable charge timeout and adaptive input power limit functions, enhancing the safety of battery charging process. The device includes 16V rated power switching and reverse blocking MOSFETs with extremely low ON resistance, ensuring high charge efficiency and simple peripheral circuit design.

Short-circuit, charge timeout and temperature protection are provided for reliable operation.

The open-drain STAT output can be used to indicate the battery state of charge.

The SY20741B is available in a compact QFN3x3 package.

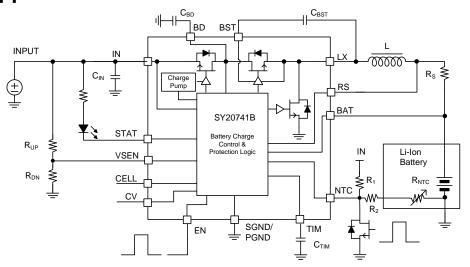
Features

- Adaptive Input Power Limit for 4-14V Input Voltage Range
- 4.2V and 4.35V Selectable Cell Termination Voltage
- Integrated Synchronous Buck and Reverse Blocking MOSFET with 16V Rating
- Maximum 2.5A Programmable Charging Current
- Supports Single-Cell or Two-Cell Battery **Packs**
- **External Shutdown Function**
- Input Voltage UVLO and OVP
- Thermal Fold-Back Protection
- Overtemperature Protection
- **Battery Short-Circuit Protection**
- **Programmable Charge Timeout**
- Charge Status Indication
- Low Profile QFN3x3 Package for Portable **Applications**

Applications

- Power Banks
- Mobile phones, Tablets
- Li-Ion Battery powered IoT devices
- Game Players
- **Notebooks**

Typical Application

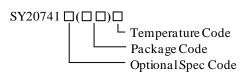




High Efficiency, 2.5A, Multi-Cell Li-Ion Battery Charger

Figure 1. Schematic Diagram

Ordering Information



| Ordering Number | Package Type | Top Mark |
|-----------------|-----------------|---------------|
| SY20741BQDC | QFN3×3-16 | cT <i>xyz</i> |

Device code: cT

x=year code, y=week code, z= lot number code

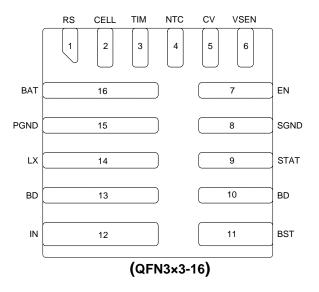


Figure 2. Package Pinout

Pinout (Top View)

| Pin Name | Pin Number | Description |
|-------------|---------------|---|
| RS | 1 | Charge current sense resistor positive pin. The sensed voltage drop between RS and BAT is used for charge current regulation and charge termination detection. |
| CELL | 2 | Battery voltage selection pin. Leave floating for two-cell batteries. Connect to GND for single-cell batteries. The pin can't be pulled high to any bias voltage higher than 3.3V. |
| TIM | 3 | Charge timeout programming pin. Connect this pin with a capacitor to the ground to program the timeout protection threshold. The internal current source charges the capacitor for TC mode and fast charge (CC&CV) mode to program the charge time limit. TC charge time limit is about 1/9 of the fast charge time. |
| NTC | 4 | Battery thermal sense pin. The voltage on the NTC pin is sensed for battery thermal protection. The UTP threshold is typically 76% of V_{IN} , and the OTP threshold is typically 45% of V_{IN} . The NTC pin can also be used for the adaptive input power limit reference refresh. The adaptive input power limit threshold will be refreshed when NTC is pulled low for more than 100ms. The SY20741B sets the charge current to the trickle value; the device will refresh the adaptive input power limit threshold according to the input voltage. For an input higher than 6V, the device will clamp the input voltage at V_{IN} -0.6V by regulating the duty cycle of the buck converter. For an input lower than 6V, the clamped input voltage is set by the VSEN pin. |





| CV | 5 | Battery CV voltage selection pin. |
|------|--------|---|
| VSEN | 6 | Input voltage sense pin for adaptive input power limit. If the voltage drops to the internal 1.17V reference voltage, V _{IN} will be clamped to the setting value and the input current will be limited. |
| EN | 7 | Enable control input pin. Drive to logic high to enable and low logic to disable. |
| SGND | 8 | Signal ground pin. |
| STAT | 9 | Charge status indication pin. Open drain output. Pull high to IN through a LED to indicate the charge is in progress. When the charge is complete, the LED turns off. |
| BD | 10, 13 | Connected to the drain of internal blocking MOSFET. Bypass with at least a 10µF ceramic cap to GND. |
| BST | 11 | Bootstrap pin. Supply for the MOSFET's gate driver. Decouple this pin to LX with a 0.1μF ceramic cap. |
| IN | 12 | DC power input pin. Connect a MLCC from this pin to the ground to decouple high-frequency noise. This pin has OVP and UVLO functions to make the charger operate within a safe input voltage area. |
| LX | 14 | Switch node pin. Connect to external inductor. |
| PGND | 15 | Power ground pin. |
| BAT | 16 | Battery voltage sense pin. |



Absolute Maximum Ratings (Note 1) IN, BAT, LX, NTC, STAT, BD, EN, CV, VSEN ------ 18V TIM, CELL------ 4V BST-LX Voltage ------ 4V RS ------ BAT-0.3~BAT+0.3V LX Pin Current Continuous ------ 5A Power Dissipation, PD @ TA = 25°C, QFN3×3----- 2.1W Package Thermal Resistance (Note 2) heta JA ------ 48 °C/W θ_{.IC} ------- 4 °C/W Lead Temperature (Soldering, 10 sec.) ------ 260°C **Recommended Operating Conditions** (Note 3) IN ------- 4V to 14V BAT, LX, NTC, STAT, BD, EN, CV, VSEN------0V to 16V TIM, CELL------ 0V to 3.3V BST-LX Voltage ----- 0V to 3.3V RS ------ BAT-0.25~BAT+0.25V LX Pin Current Continuous ------ 4.5A Junction Temperature Range ------ -40°C to 100°C Ambient Temperature Range -------40°C to 85°C



Electrical Characteristics

 $(T_A=25^{\circ}C,\ V_{IN}=5V,\ GND=0V,\ C_{IN}=10\mu F,\ L=2.2\mu H,\ R_S=10m\Omega,\ C_{TIM}=330nF,\ unless\ otherwise\ specified.)$

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|---|-----------------------|---|-------|-------|-------|----------------|
| Bias Supply (V _{IN}) | | | | | | |
| Supply Voltage Operation Range | V _{IN} | | 4 | | 14 | V |
| Input Voltage Lockout Threshold | Vuvlo | V _{IN} rising and measured from IN to ground | | | 4 | V |
| Input Voltage Lockout Hysteresis | $\Delta V_{\sf UVLO}$ | Measured from IN to ground | | 0.2 | | V |
| Input Over Voltage Protection | VIN_OVP | V _{IN} rising and measured from IN to ground | 12.9 | | | V |
| Input Over Voltage Protection Hysteresis | ΔV_{OVP} | Measured from IN to ground | | 0.5 | | V |
| Quiescent Current | | | | | | |
| Battery Discharge Current | I _{BAT} | V _{IN} absent or EN=Low | | 5 | 10 | μA |
| Input Quiescent Current | I _{IN} | Disable charge | | 0.8 | 1.1 | mA |
| Oscillator and PWM | | | | | | |
| Switching Frequency | fsw | | | 500 | | kHz |
| Power MOSFET | I . | 1 | I | I | I. | |
| R _{DS(ON)} of Main N-FET | R _{NFET_M} | | | 30 | | mΩ |
| R _{DS(ON)} of Rectified N-FET | R _{NFET_R} | | | 55 | | mΩ |
| R _{DS(ON)} of Blocking N-FET | R _{NFET_B} | | | 45 | | mΩ |
| Voltage Regulation | | 1 | l | I | I. | |
| | V _{BAT_REG} | 1-cell battery, V _{CV} <0.4V | 4.078 | 4.1 | 4.122 | |
| Datta Ohanna Malta na | | 1-cell battery, V _{CV} >1.5V | 4.223 | 4.246 | 4.269 | |
| Battery Charge Voltage | | 2-cell battery, V _{CV} <0.4V | 8.159 | 8.2 | 8.241 | V |
| | | 2-cell battery, V _{CV} >1.5V | 8.451 | 8.493 | 8.535 | |
| Recharge Threshold Refer to | ΔV_{RCH} | 1-cell battery | 50 | 100 | 150 | mV |
| V _{BAT_REG} | ΔVRCH | 2-cell battery | 100 | 200 | 300 | IIIV |
| Trickle Charge Rising Edge | V _{TRK} | 1-cell battery | 2.65 | 2.75 | 2.85 | V |
| Threshold | | 2-cell battery | 5.3 | 5.5 | 5.7 | V |
| Adaptive Input Current REF Modi | fy | | 1 | ı | 1 | |
| NTC Voltage Threshold for Adaptive Input Current Reference Refresh | V _{NTC} | NTC falling edge | 0.4 | | | V |
| NTC Low Time to Enable the Adaptive Input Current Refresh | t _{DET} | Low pulse width | | 100 | | ms |
| Charge Current | T | | T | Т | T | |
| Charge Current Accuracy for Constant Current Mode | Icc | I _{CC} =25mV/R _S | -10 | | 10 | % |
| Charge Current Accuracy for Trickle Current Mode | Ітс | I _{TC} =2.5mV/R _S | -50 | | 50 | % |
| Termination Current | I _{TERM} | I _{TERM} =2.5mV/R _S | -50 | | 50 | % |
| Output Voltage OVP | | | | | | |
| Output Voltage OVP Threshold | V _{O_OVP} | | 105% | 110% | 115% | V_{BAT_REG} |
| Adaptive Input Power Limit Reference | | | | | | |
| Reference for Adaptive Input Power Limit | Vsen | | 1.13 | 1.17 | 1.21 | V |
| The Adaptive Input Power Limit Reference is V _{IN} -ΔV _{AICL} | ΔV_{AICL} | NTC pulls lower than 100ms, and V _{IN} is higher than 6V | | 600 | | mV |



| Timer | | | | | | |
|---|----------------------|--|------|------|------|------|
| Trickle Current Charge | t _{TC} | | 0.34 | 0.5 | 0.67 | hour |
| Timeout | TIC . | | 0.54 | 0.5 | 0.07 | Hour |
| Constant Current Charge Timeout | tcc | | 3.1 | 4.5 | 6.2 | hour |
| Charge Mode Change Delay Time | t _{MC} | | | 30 | | ms |
| Termination Delay Time | tterm | | | 30 | | ms |
| Recharge Time Delay | trchg | | | 30 | | ms |
| Short Circuit Protection | | 1 | l | | | |
| Output Short Protection Threshold, Falling Edge | V _{SHORT} | | 1.7 | 2.00 | 2.3 | V |
| Auto Shut Down | | | | | | |
| Auto Shutdown Voltage Threshold | Vasd | V _{IN} falls, measured from IN to BAT | 40 | 90 | 180 | >/ |
| Auto Shutdown Voltage Threshold Hysteresis | ΔV_{ASD} | V _{IN} rises, measured from IN to BAT | | 65 | | mV |
| Logical Control | | | I. | l | | I |
| High Level Logic for Enable Control | VENH | | 1.5 | | | V |
| Low Level Logic for Enable Control | V _{ENL} | | | | 0.4 | V |
| High Level Logic for CV | V _{CVH} | | 1.5 | | | V |
| Low Level Logic for CV | V _{CVL} | | | | 0.4 | V |
| Battery Thermal Protection NTC | | | | | | |
| Under Temperature Protection | V _{NTC_UTP} | | 75% | 76% | 77% | |
| Under Temperature Protection Hysteresis | VNTC_UTP_HYS | Falling edge | | 5% | | ., |
| Over Temperature Protection | V _{NTC_OTP} | | 44% | 45% | 46% | Vin |
| Over Temperature Protection Hysteresis | VNTC_OTP_HYS | Rising edge | | 1.5% | | |
| Thermal Fold-back and Thermal | Shutdown | | • | • | | |
| Thermal Fold-back Threshold | T _{Fold} | | | 120 | | ٥C |
| Thermal Fold-back Hysteresis Falling Edge | T _{FoldHYS} | | | 20 | | ۰C |
| Thermal Fold-back Ratio | I Fold | | | 0.25 | | Icc |
| Thermal Shutdown Temperature | T _{SD} | Rising threshold | | 160 | | °C |
| Thermal Shutdown Temperature Hysteresis | T _{SDHYS} | | | 30 | | °C |

Note 1: Stresses beyond the "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

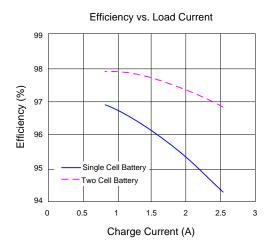
Note 2: θ JA is measured in the natural convection at $T_A = 25^{\circ}C$ on a low effective four-layer thermal conductivity test board of JEDEC 51-3 thermal measurement standard.

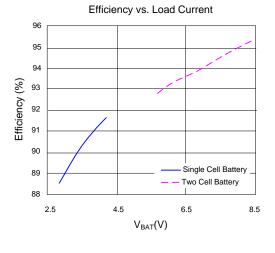
Note 3: The device is not guaranteed to function outside its operating conditions.

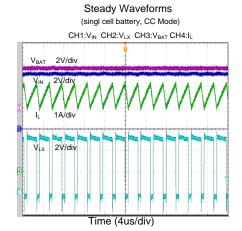


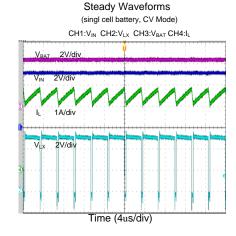
Typical Performance Characteristics

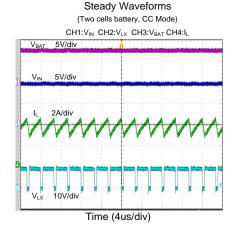
 $(T_A=25^{\circ}C, V_{IN}=5V, V_{BAT}=3.6V \text{ for single-cell battery applications. } V_{IN}=9V, V_{BAT}=7.6V \text{ for two-cell battery applications.}$ $R_s=10m\Omega, C_{TIM}=330nf, \text{ unless otherwise specified.})$

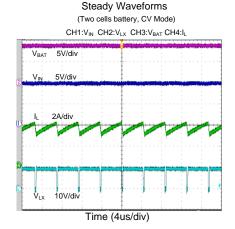








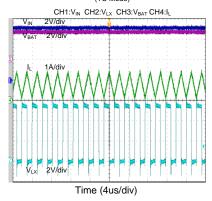




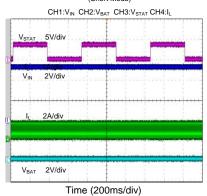




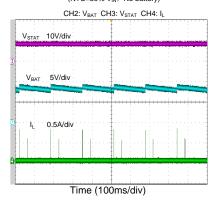
Steady Waveforms (TC Mode)



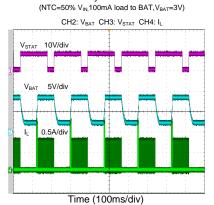
Steady Waveforms (Short Mode)



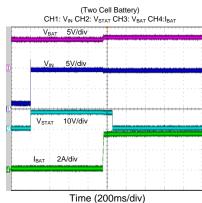
Steady Waveform When No Battery (NTC=50% V_{IN} , No battery)



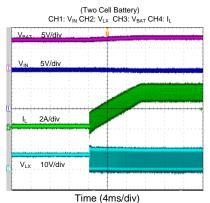
Steady Waveform



Power On



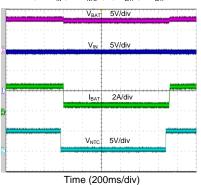
Soft Start



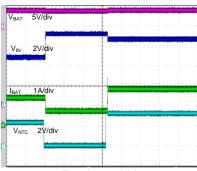




 $\begin{array}{c} \text{Low Pulse On NTC Pin} \\ (\text{V}_{\text{IN}}\text{=9V V}_{\text{BAT}}\text{=7.6V} \) \\ \text{CH1: V}_{\text{IN}}\text{ CH2: V}_{\text{NTC}}\text{ CH3: V}_{\text{BAT}}\text{ CH4:I}_{\text{BAT}} \end{array}$



Adaptive Input Power Limit Reference Refresh (Input Adapter changes to 7V/1A V_{BAT}=3.6V)
CH1: V_{IN} CH2:V_{MTC} CH3: V_{BAT} CH4:I_{BAT}







Application Information

The SY20741B is a multi-cell Li-lon battery step-down charger designed for a 4-14V input range, delivering a charge current of up to 2.5A. It integrates a reverse blocking MOSFET, 500kHz synchronous buck, and full protection functions. The charge current can be adjusted using an external resistor, offering flexibility for various portable applications.

The charger features programmable charge timeout and adaptive input power limit functions, enhancing the safety of battery charging.

The device includes 16V rated power switching and reverse blocking MOSFETs with extremely low ON resistance, ensuring high charge efficiency and simple peripheral circuit design.

Charging Status Indication Description:

STAT operates as an open-drain output, requiring a pullup resistor for charging status indication. To implement this, connect an LED in series with a current limiting resistor from the IN net to the STAT pin. An illuminated LED signifies "Charge-in-Process," an unlit LED indicates "Charge Done" and a flashing LED with a frequency of 1.3Hz means "Fault Mode."

- 1. Charge in progress:
 - STAT pin is pulled low.
- 2. Charge Done:
 - STAT pin is high impedance.
- 3. Fault Mode:
 - In Fault Mode, the LED alternates between ON and OFF at a frequency of 1.3Hz.
 - Faults leading to Fault Mode include input OVP, BAT OVP, BAT short, BAT UTP, BAT OTP, timeout, and thermal shutdown.

Buck Charger Switching Mode Operation

Switching Mode Control Strategy:

The SY20741B utilizes pseudo-constant frequency control to simplify the internal close-loop compensation design. The frequency is set to 500kHz, enabling the use of small size external components for minimized peripheral circuit design and size optimization. Additionally, during light load operation, the OFF time of the main MOSFET is extended to achieve frequency foldback for improved efficiency.

Charger Operation:

When connected to an adapter, the SY20741B functions as a synchronous buck mode battery charger.

The charger control loops adapts to various charging modes based on the battery state, including constant current charge mode, constant voltage charge mode, trickle charge mode as well as battery faults including battery short. The charge curve graph below illustrates the corresponding charge currents for each mode.

In the constant voltage mode, the charger halts charging if the current falls below the termination current. It resumes when the battery voltage decreases below the recharge voltage threshold.

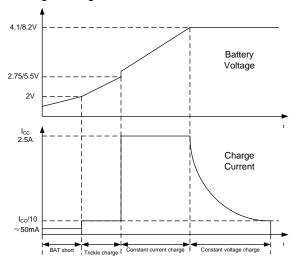


Figure 3. Battery Charge Modes

Adaptive Input Power Limit:

The SY20741B offers adaptive input power limiting, by adjusting the current based on the input voltage. The charger automatically reduces the charge current when the IN voltage drops below the adaptive input power limit reference VREF.

For a standard 5V adapter, V_{REF} is determined by the V_{SEN} pin and is calculated as follows:

$$V_{REF} = 1.17 \times \frac{R_{UP} + R_{DN}}{R_{DN}}$$

If the IN voltage is higher than 6V, V_{REF} is calculated using the equation:

$$V_{REF} = V_{IN} - \Delta V_{AICL}$$

Where:

- ΔV_{AICL} has a typical value of 0.6V.
- V_{IN} is the input voltage when the adapter is inserted.





 V_{REF} is resampled following a low pulse on the NTC pin lasting more than 100ms, provided that the adapter is consistently present.

When the NTC pin is pulled low continuously, the charge current is set to the trickle value; battery thermal protection and adaptive input power limit functions are disabled.

Charger Protection Features:

During charging, the SY20741B provides the following device and battery protection features:

Input Overvoltage Protection: SY20741B offers IN overvoltage protection. It will turn off the switching charger when an input OVP occurs. The device will resume normal operation when the fault is removed.

BAT Overvoltage Protection: SY20741B will stop charging when a BAT OVP occurs. The device will resume normal operation when the fault is removed.

Timeout Protection: The charger is designed to detect a faulty battery. If the charger operates beyond the safety time determined by C_{TIM} , it will stop charging and enter a latched-off state. Recycling the input voltage is necessary to remove this fault condition.

Battery Thermal Protection: The converter will halt switching if the NTC voltage falls below the OTP threshold while remaining above 0.4V or exceeds the UTP threshold. The device will automatically recover once the fault condition dissapears.

Thermal Shutdown Protection: The device will stop operation when the junction temperature is higher than T_{SD} (160°C typ.). The device will resume normal operation when the die temperature drops below $T_{\text{SD-}}$ T_{SDHYS} .

Design Procedure

The following paragraphs provide information on the selection process for the input capacitor (C_{IN}), BD pin decoupling (C_{BD}), output capacitor (C_{OUT}), inductor (L), NTC resistors (R1 and R2) charging current sense resistor (Rs), and the timer capacitor (C_{TIM}) based on the target application specifications.

NTC Resistor:

The SY20741B monitors battery temperature by measuring the input voltage and NTC voltage. The

controller triggers the UTP or OTP when the rate K (K= V_{NTC}/V_{IN}) reaches the threshold for UTP (K_{UT}) or OTP (K_{OT}). The temperature sensing network is shown below:

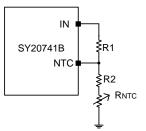


Figure 4. UTP /OTP configuration using R1 and R2

The calculation steps are:

- 1. Define K_{UT}; K_{UT} =75~77%
- 2. Define Kot: Kot =44~46%
- 3. Assume the resistance of the battery NTC thermistor is R_{UT} at the UTP threshold and R_{OT} at the OTP threshold.
- 4. Calculate R2:

$$R2 = \frac{Kot(1-Kut)Rut-Kut(1-Kot)Rot}{Kut-Kot}$$

5. Calculate R1:

$$R1=(1/K_{OT}-1)(R2+R_{OT})$$

When typical values (K_{UT} =76% and K_{OT} =45%) are chosen, then:

The SY20741B accepts various NTC divider circuits. For the method below, R_1 and R_2 can be calculated by using the following equations:

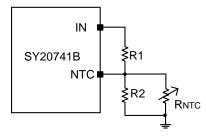


Figure 5. Alternate UTP /OTP configuration

$$R2 = \frac{R_{\text{OT}} \times R_{\text{UT}}(K_{\text{UT}} - K_{\text{OT}})}{K_{\text{OT}} \times K_{\text{UT}} \times (R_{\text{OT}} - R_{\text{UT}}) + R_{\text{UT}} \times K_{\text{OT}} - R_{\text{OT}} \times K_{\text{UT}}}$$





$$R1 = \frac{R2 \times R_{\text{UT}} \times (1 \text{-} K_{\text{UT}})}{K_{\text{UT}} \times (R2 \text{+} R_{\text{UT}})}$$

When typical values (K_{UT} =76% and K_{OT} =45%) are chosen, then:

$$R2 = \frac{0.31 R_{\text{UT}} \times R_{\text{OT}}}{0.108 \times R_{\text{UT}} \text{-} 0.418 \times R_{\text{OT}}}$$

$$R1 = \frac{0.316 R2 \times R_{\text{UT}}}{R_{\text{UT}} + R2}$$

Charging Current Sense Resistor Rs:

The charging current sense resistor $R_{\rm S}$ is calculated as follows:

$$R_{s} = \frac{25mV}{I_{CC}}$$

Where:

- The lcc is the battery's constant charging current, unit: A.
- Units are in mΩ

Timer Capacitor CTIM:

The charger provides a programmable safety charging timer. The charging time is programmed by the capacitor connected between the TIM pin and GND. The capacitance is calculated as follows:

$$C_{TIM}=2\times10^{-11}\,S\times T_{CC}$$

Where:

- T_{CC} is the permitted fast charging time, unit: s.
- Capacitor units are in F.

Input Capacitor C_{IN}:

The ripple current through the input capacitor can be estimated using the following equation:

$$I_{C_{BD}_MIN} = I_{CC} \sqrt{D(1-D)}$$

To minimize system noise, place a typical X7R or better-grade ceramic capacitor close to the IN and GND pins. Minimize the loop area formed by C_{IN} and the IN/GND pins. The capacitor should be selected based on the ability to handle the ripple current. Paralleling capacitors can be used to meet the ripple requirements. A value of 10 μF is sufficient for most applications.

BD Pin Decoupling CBD:

Place a typical X7R or a better-grade ceramic capacitor close to the BD and GND pins. Minimize the loop area formed by C_{BD} and the BD/GND pins. A value of 10 μ F is recommended for most applications.

Output Capacitor Соит:

The output capacitor is selected to handle the output ripple noise requirements. Both steady-state ripple and transient requirements must be considered when selecting this capacitor. For the best performance, it is recommended to use an X7R or a better-grade ceramic capacitor with at least 10µF capacitance.

Output Inductor L:

When selecting the inductor, consider the following factors:

- Choose the inductance to achieve the desired ripple current. It is suggested that the ripple current be approximately 40% of the average input current.
- 2. The minimum inductance is calculated as follows:

$$L = \frac{V_{\text{OUT}} \times (1 - V_{\text{OUT}} / V_{\text{IN,MAX}})}{F_{\text{SW}} \times I_{\text{OUT,MAX}} \times 40\%}$$

Where:

- F_{SW} is the switching frequency.
- I_{OUT, MAX} is the maximum load current.

The SY20741B is tolerant to different ripple current amplitudes. Therefore, the final inductance selection can deviate slightly from the calculated value without significantly affecting performance.

3. The saturation current rating of the inductor must be selected to be greater than the peak inductor current under full load conditions.

$$I_{\text{SAT,MIN}} > I_{\text{OUT,MAX}} + \frac{V_{\text{OUT}} \times (1 - V_{\text{OUT}} / V_{\text{IN, MAX}})}{2 \times F_{\text{SW}} \times L}$$

4. The DC resistance (DCR) of the inductor and the core loss at the switching frequency should be sufficiently low to meet the desired efficiency requirements. It is recommended to select an inductor with DCR < $20m\Omega$.

The SY20741B includes internal compensation circuits that influence the choice of the inductor. It is advised to avoid inductors outside the range of $0.68\mu H$ to $3.3\mu H$. A $2.2\mu H$ inductor is well-suited for typical applications and covers most use cases.



PCB Layout Guide:

For best performance of the SY20741B, the following guidelines must be followed:

- Enhance thermal and noise performance by maximizing the PCB copper area connected to the GND pin.
- Place C_{BD} and L close to the device to minimize noise problems and improve efficiency.

- 3. Place C_{BD} close to the BD and GND pins. The loop area formed by C_{BD} and GND must be minimized. Refer to Figure 2 below for the recommended C_{BD} layout design.
- 4. Minimize the PCB copper area associated with the LX pin to reduce EMI.
- The capacitor (C_{TIM}) and the trace connecting to the TIM pin must not be adjacent to the LX net on the PCB layout to avoid noise problems.

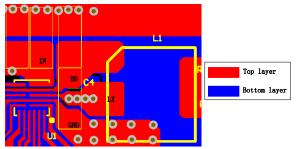


Figure 2. C_{BD} Layout Suggestion

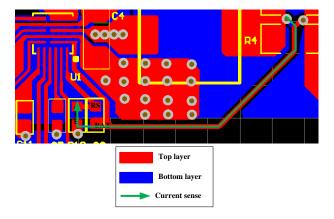
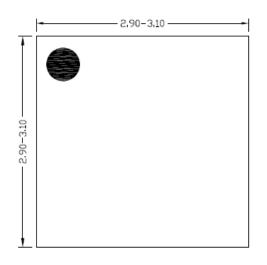
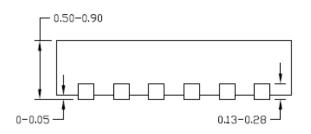


Figure 3. PCB Layout Suggestion

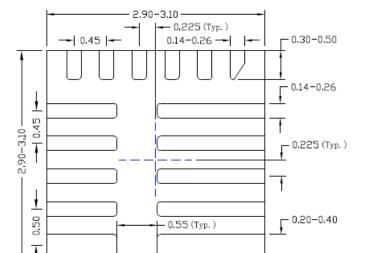


QFN3×3-16 Package Outline Drawing



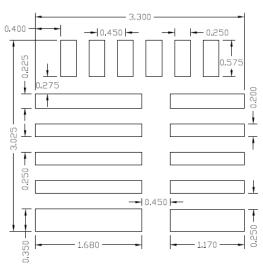


Top View



Bottom View

Side View



Recommended PCB Layout (Reference Only)

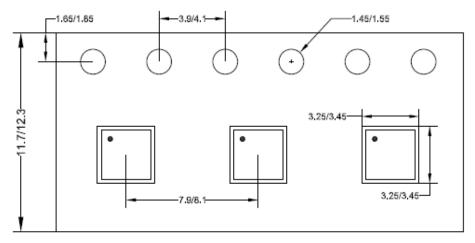
Note: All dimensions are in millimeters and exclude mold flash and metal burr.

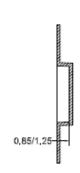
0.87-1.07



Taping & Reel Specification

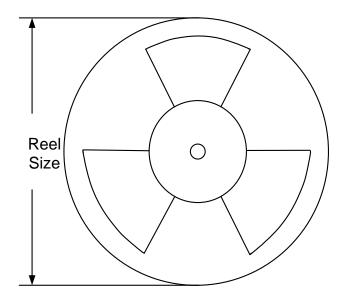
QFN3x3 Taping Orientation





Feeding direction -

Carrier Tape & Reel Specification for Packages



| Package type | Tape width (mm) | Pocket pitch(mm) | Reel size (Inch) | Trailer length(mm) | Leader length (mm) | Qty per reel |
|--------------|-----------------|------------------|---------------------|-----------------------|-----------------------|-----------------|
| QFN3×3 | 12 | 8 | 13" | 400 | 400 | 5000 |



Revision History

The revision history provided is for informational purpose only and is believed to be accurate, however, not warranted. Please make sure that you have the latest revision.

| Date | Revision | Change |
|-------------------|---------------|--|
| Mar.26, 2020 | Revision 0.9B | Change "V _{NTC_UTP} " min value from 74% to 75%, typical value from 75% to 76%, max value from 76% to 77% |
| ,Nov.16, 2017 | Revision 0.9A | 1. Change pin VSEN description from " If the voltage drops to internal 1.19V reference voltage" to "If the voltage drops to internal 1.17V reference voltage". |
| | | 2.Change " NNTC_UTP" min value from 70% to 74%, max value from 80% to 76%. |
| | | 3.Change " NNTC_OTP" min value from 43% to 44%, max value from 47% to 46%. |
| | | 4. In Page 10, Change from "Define KUT, KUT =70~80%" to "Define KUT, KUT =74~76%", change from "Define KOT, KOT =43~47%" to "Define KOT, KOT =44~46%". |
| | | 5. In page 10, chage the formula fro $R_s = \frac{25}{I_{CC}}$ $R_s = \frac{25 \text{mV}}{I_{CC}}$ |
| | | 6. In page 11, change the formula from "CTIM=2×10-11TCC" to "CTIM=2×10-11S×TCC". |
| Sept. 22, 2017 | Revision 0.9 | Initial Release |





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